CD54HC573, CD74HC573 OCTAL TRANSPARENT D-TYPE LATCHES WITH 3-STATE OUTPUTS

CD54HC573...F PACKAGE

CD74HC573...E OR M PACKAGE

(TOP VIEW)

<u>oe</u> l

1D **∏** 2

2D **∏** 3

3D **∏** 4

4D 🛮 5

5D 🛮 6

7D **∏** 8

8D 🛮 9

GND ∏

6D Π

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20 VCC

19**∏** 1Q

18**∏** 2Q

17 🛮 3Q

16 🛮 4Q

15**∏** 5Q

14**∏** 6Q

13 7Q 12 8Q

11 **∏** LE

- 2-V to 6-V V_{CC} Operation
- Wide Operating Temperature Range of -55°C to 125°C
- 3-State Outputs Directly Drive Bus Lines
- Balanced Propagation Delays and Transition Times
- Bus Driver Outputs Drive Up To 15 LS-TTL Loads
- Significant Power Reduction Compared to LS-TTL Logic ICs

description/ordering information

The 'HC573 devices are octal transparent D-type latches designed for 2-V to 6-V V_{CC} operation.

When the latch-enable (LE) input is high, the Q outputs follow the data (D) inputs. When LE is low, the Q outputs are latched at the logic levels of the D inputs.

A buffered output-enable (\overline{OE}) input can be used to place the eight outputs in either a normal logic state (high or low) or the high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and increased drive provide the capability to drive bus lines without interface or pullup components.

OE does not affect the internal operations of the latches. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

ORDERING INFORMATION

TA	PACKAGET		PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
	PDIP – E	Tube	CD74HC573E	CD74HC573E		
-55°C to 125°C	SOIC - M	Tube	CD74HC573M	HC573M		
		Tape and reel	CD74HC573M96	TIC373WI		
	CDIP – F	Tube	CD54HC573F3A	CD54HC573F3A		

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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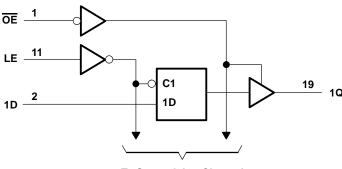


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FUNCTION TABLE (each latch)

	OUTPUT		
Œ	LE	D	Q
L	Н	Н	Н
L	Н	L	L
L	L	Χ	Q ₀
Н	Χ	Χ	Z

logic diagram (positive logic)



To Seven Other Channels

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}	–0.5 V to 7 V
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$) (see Note 1)	±20 mA
Output clamp current, I _{OK} (V _O < 0 or V _O > V _{CC}) (see Note 1)	±20 mA
Continuous output drain current per output, I_O ($V_O = 0$ to V_{CC})	±35 mA
Continuous output source or sink current per output, $I_O(V_O = 0 \text{ to } V_{CC})$	±25 mA
Continuous current through V _{CC} or GND	±50 mA
Package thermal impedance, θ _{JA} (see Note 2): E package	69°C/W
M package	58°C/W
Storage temperature range, T _{Stg}	–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
 - 2. The package thermal impedance is calculated in accordance with JESD 51-7.



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recommended operating conditions (see Note 3)

			T _A = 1	T _A = 25°C		55°C 25°C	T _A = -40°C TO 85°C		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	
VCC	Supply voltage		2	6	2	6	2	6	V
		$V_{CC} = 2 V$	1.5		1.5		1.5		
٧ıH	High-level input voltage	$V_{CC} = 4.5 V$	3.15		3.15		3.15		V
	V _{CC} = 6 V		4.2		4.2		4.2]
		V _{CC} = 2 V		0.5		0.5		0.5	
٧ _{IL}	Low-level input voltage	V _{CC} = 4.5 V		1.35		1.35		1.35	V
		VCC = 6 V		1.8		1.8		1.8	
٧ _I	Input voltage		0	VCC	0	VCC	0	VCC	V
٧o	Output voltage		0	VCC	0	VCC	0	VCC	V
		V _{CC} = 2 V		1000		1000		1000	
t _t	Input transition (rise and fall) time	V _{CC} = 4.5 V		500		500		500	ns
	V _{CC} = 6 V			400		400		400	

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST	TEST CONDITIONS		T _A =	T _A = 25°C		T _A = -55°C TO 125°C		T _A = -40°C TO 85°C	
					MIN MAX		MAX	MIN	MAX	
			2 V	1.9		1.9		1.9		
		$I_{OH} = -20 \mu A$	4.5 V	4.4		4.4		4.4		
V_{OH}	$V_I = V_{IH}$ or V_{IL}		6 V	5.9		5.9		5.9		٧
		$I_{OH} = -6 \text{ mA}$	4.5 V	3.98		3.7		3.84		
		$I_{OH} = -7.8 \text{ mA}$	6 V	5.48		5.2		5.34		
		I _{OL} = 20 μA	2 V		0.1		0.1		0.1	
			4.5 V		0.1		0.1		0.1	
V_{OL}	$V_I = V_{IH} \text{ or } V_{IL}$		6 V		0.1		0.1		0.1	V
		I _{OL} = 6 mA	4.5 V		0.26		0.4		0.33	
		$I_{OL} = 7.8 \text{ mA}$	6 V		0.26		0.4		0.33	
lj	VI = VCC or 0		6 V		±0.1		±1		±1	μΑ
loz	VO = VCC or 0		6 V		±0.5		±10		±5	μΑ
Icc	$V_I = V_{CC}$ or 0,	IO = 0	6 V		8		160		80	μΑ
Ci					10		10		10	pF
Co					20		20		20	pF

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timing requirements over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

		Vcc	T _A = 2	25°C	T _A = -		T _A = -4 TO 85		UNIT
		00	MIN	MAX	MIN	MAX	MIN	MAX	
	Pulse duration, LE high	2 V	80		120		100		ns
t _W		4.5 V	16		24		20		
		6 V	14		20		17		
	Setup time, data before LE↓	2 V	50		75		65		ns
t _{su}		4.5 V	10		15		13		
		6 V	9		13		11		
	Hold time, data after LE↓	2 V	40		60		50		ns
t _h		4.5 V	8		12		10		
		6 V	7		10		9		

switching characteristics over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

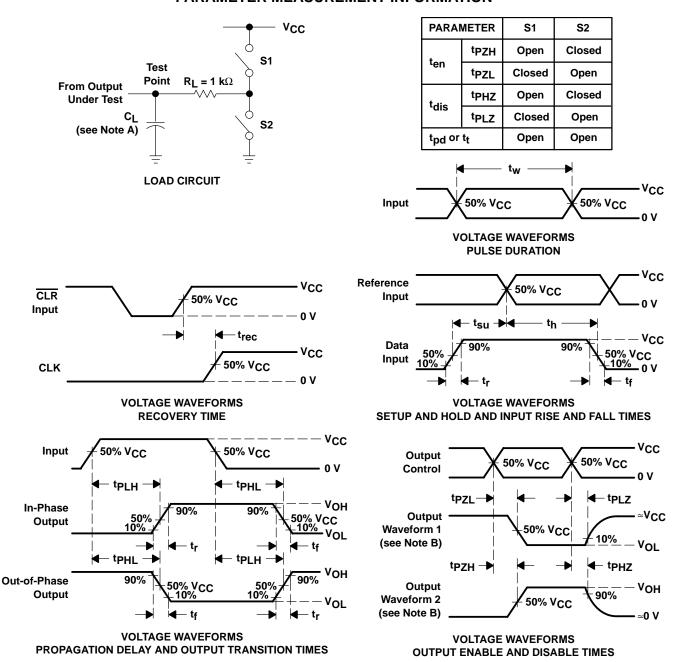
PARAMETER	FROM	FROM TO LOAD VCC TA = 25°C CAPACITANCE		T _A = -55°C TO 125°C	T _A = -40°C TO 85°C	UNIT					
	(1141 01)	(001101)	CALACITANCE		MIN MAX	MIN MAX	MIN MAX				
					2 V	175	265	220			
	D	Q	C _L = 50 pF	4.5 V	35	53	44				
. .				6 V	30	45	37	no			
^t pd			C _L = 50 pF	2 V	175	265	220	ns			
	LE	Q		4.5 V	35	53	44				
							(6 V	30	45
	ŌĒ						2 V	150	225	190	
t _{en}		Q	C _L = 50 pF	C _L = 50 pF	4.5 V	30	45	38	ns		
					6 V	26	38	33			
	ŌĒ		C _L = 50 pF	C _L = 50 pF	2 V	150	225	190			
^t dis		Q			$C_{L} = 50 pF$	4.5 V	30	45	38	ns	
						6 V	26	38	33		
				2 V	60	90	75				
t _t		Q	C _L = 50 pF	C _L = 50 pF	4.5 V	12	18	15	ns		
				6 V	10	15	13				

operating characteristics, $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$

	PARAMETER	TYP	UNIT
Ср	od Power dissipation capacitance	51	pF



PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and test-fixture capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, Z_O = 50 Ω , t_f = 6 ns.
- D. For clock inputs, f_{max} is measured with the input duty cycle at 50%.
- E. The outputs are measured one at a time with one input transition per measurement.
- F. tpLz and tpHz are the same as tdis.
- G. tpzL and tpzH are the same as ten.
- H. tpLH and tpHL are the same as tpd.

Figure 1. Load Circuit and Voltage Waveforms



14 LEADS SHOWN



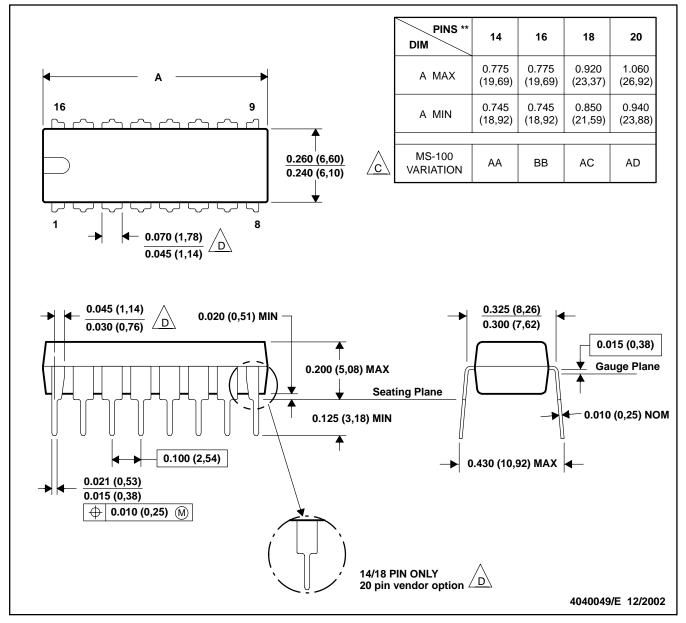
NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

N (R-PDIP-T**)

16 PINS SHOWN

PLASTIC DUAL-IN-LINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

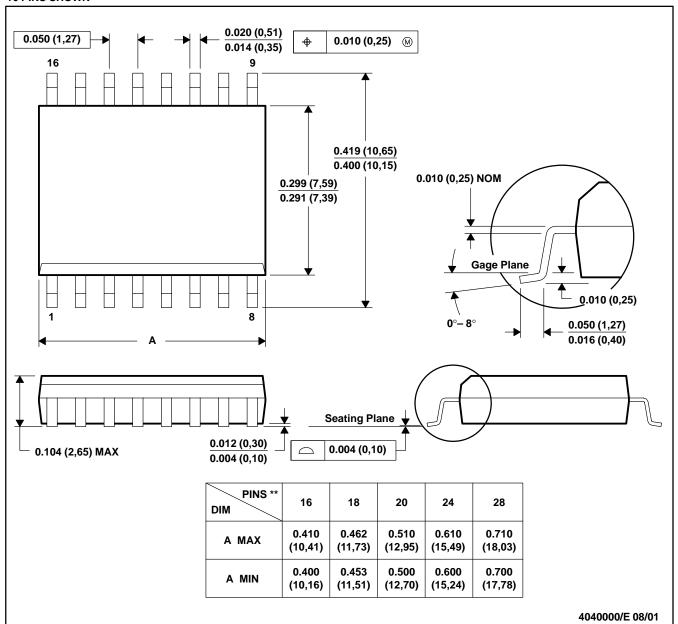
Falls within JEDEC MS-001, except 18 and 20 pin minimum body Irngth (Dim A).

The 20 pin end lead shoulder width is a vendor option, either half or full width.

DW (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

16 PINS SHOWN



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).

D. Falls within JEDEC MS-013

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